## imall

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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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## DATASHEET

## 8 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER EL827 Series



## Features:

- Current transfer ratio (CTR: 50~600% at  $I_F$  =5mA,  $V_{CE}$  =5V)
- High isolation voltage between input
- and output (Viso=5000 V rms)
- Compact small outline package
- Pb free and RoHS compliant.
- UL approved (No. E214129)
- VDE approved (No. 132249)
- SEMKÖ approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CSA approved
- CQC approved

## Description

The EL827series devices each of consist of an infrared emitting diodes, optically coupled to a phototransistor detector. They are packaged in a 8-pin DIP package and available in wide-lead spacing and

SMD option.

## Applications

- Programmable controllers
- System appliances, measuring instruments
- Telecommunication equipments
- Home appliances, such as fan heaters, etc.
- Signal transmission between circuits of different potentials and impedances

### **Schematic**



Pin Configuration

- 1, 3. Anode
- 2, 4. Cathode 5, 7. Emitter
- 6, 8. Collector

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## Absolute Maximum Ratings (Ta=25℃)

	Parameter	Symbol	Rating	Unit
	Forward current	I <sub>F</sub>	60	mA
Input	Peak forward current (1us, pulse)	I <sub>FP</sub>	1	А
	Reverse voltage	V <sub>R</sub>	6	V
	Power dissipation	P <sub>D</sub>	100	mW
Output	Power dissipation	P <sub>C</sub>	150	mW
	Collector current	I <sub>C</sub>	50	mA
	Collector-Emitter voltage	V <sub>CEO</sub>	80	V
	Emitter-Collector voltage	V <sub>ECO</sub>	7	V
Total power dissipation		P <sub>TOT</sub>	200	mW
Isolation voltage <sup>*1</sup>		V <sub>ISO</sub>	5000	V rms
Operating temperature		T <sub>OPR</sub>	-55 to 110	°C
Storage temperature		T <sub>STG</sub>	-55 to 125	°C
Soldering temperature <sup>*2</sup>		T <sub>SOL</sub>	260	°C

#### Notes:

\*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 & 3, 4are shorted together, and pins 5, 6 & 7, 8 are shorted together.

\*2 For 10 seconds

## Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input							
Parameter	Symbol	Min.	Тур.*	Max.	Unit	Condition	
Forward Voltage	V <sub>F</sub>	-	1.2	1.4	V	I <sub>F</sub> = 20mA	
Reverse Current	I <sub>R</sub>	-	-	10	μA	$V_R = 4V$	
Input capacitance	Cin	-	30	250	pF	V = 0, f = 1kHz	
Output							
Parameter	Symbol	Min.	Тур.*	Max.	Unit	Condition	
Collector-Emitter dark current	I <sub>CEO</sub>	-	-	100	nA	$V_{CE} = 20V, I_F = 0mA$	
Collector-Emitter breakdown voltage	$BV_{CEO}$	80	-	-	V	$I_{\rm C} = 0.1  {\rm mA}$	
Emitter-Collector breakdown voltage	$BV_{ECO}$	7	-	-	V	I <sub>E</sub> = 0.1mA	
Transfer Characteristics							
Parameter	Symbol	Min	Тур.	Max.	Unit	Condition	
Current Transfer ratio	CTR	50	-	600	%	$I_F = 5mA$ , $V_{CE} = 5V$	
Collector-Emitter saturation voltage	$V_{CE(sat)}$	-	0.1	0.2	V	$I_{F} = 20mA$ , $I_{C} = 1mA$	
Isolation resistance	R <sub>IO</sub>	5×10 <sup>10</sup>	-	-	Ω	V <sub>IO</sub> = 500Vdc, 40~60% R.H.	
Floating capacitance	C <sub>IO</sub>	-	0.6	1.0	pF	$V_{IO} = 0$ , f = 1MHz	
Cut-off frequency	fc	-	80	-	kHz	$V_{CE} = 5V, I_{C} = 2mA$ $R_{L} = 100\Omega, -3dB$	
Rise time	tr	-	3	18	μs	$V_{CE} = 2V, I_{C} = 2mA.$	
Fall time	t <sub>f</sub>	-	4	18	μs	R <sub>L</sub> = 100Ω	

\* Typical values at  $T_a = 25^{\circ}C$ 

## **Typical Electro-Optical Characteristics Curves**





Figure 3. Normalized Current Transfer Ratio vs Forward Current





Figure 4. Normalized Collector Current vs Ambient Temperature





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## **Order Information**

**Part Number** 



## Note

- X = Lead form option (S, S1, M or none)
- Z = Tape and reel option (TA, TB or none)
- V = VDE safety (optional)

Option	Description	Packing quantity	
None	Standard DIP-8	45 units per tube	
М	Wide lead bend (0.4 inch spacing)	45 units per tube	
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel	
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel	
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel	
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option 1000 units per re-		

## Package Dimension (Dimensions in mm)

## **Standard DIP Type**



#### **Option M Type**



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## **Option S Type**







## **Option S1 Type**





## Recommended pad layout for surface mount leadform



## **Device Marking**



#### Notes

EL827	denotes Device Number
Y	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)

## **Tape & Reel Packing Specifications**



Direction of feed from reel



Direction of feed from reel



## **Tape dimensions**



Dimension No.	Α	В	Do	D1	Е	F
Dimension(mm)	10.4±0.1	10.0±0.1	1.5±0.1	1.5+0.25 -0.1	1.75±0.1	7.5±0.1
Dimension No.	Ро	P1	P2	t	W	к
Dimension(mm)	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0±0.3	4.5±0.1



## **Precautions for Use**

#### 1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

### Preheat

Other	
Time $(T_{smin} \text{ to } T_{smax}) (t_s)$ Average ramp-up rate $(T_{smax} \text{ to } T_p)$	
Temperature max (T <sub>smax</sub> )	
Temperature min (T <sub>smin</sub> )	

Liquidus Temperature (TL)
Time above Liquidus Temperature (t $_{L}$ )
Peak Temperature (T <sub>P</sub> )
Time within 5 °C of Actual Peak Temperature: $T_P$ - 5°C
Ramp- Down Rate from Peak Temperature
Time 25°C to peak temperature Reflow times

Reference: IPC/JEDEC J-STD-020D

150 °C 200°C 60-120 seconds 3 °C/second max 217 °C 60-100 sec

260°C 30 s 6°C /second max. 8 minutes max. 3 times

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